

Amendments to the Specification:

The following Abstract will replace the Abstract in the application:

ABSTRACT

~~The object of the present invention is to provide a multilayer flexible wiring board which is capable of effecting interlaminar connection with certainty, has high reliability and allows lamination of outer layer wiring boards. According to the present invention, there is provided a~~ A multilayer flexible wiring board including (1) plural single-sided wiring boards each having a wiring pattern on one side of the corresponding substrate and two-layer conductor posts projecting from the wiring pattern to the side of the substrate opposite from the wiring pattern, wherein the substrates other than that of the outermost layer have the pads to be connected to the two-layer conductor posts on the side opposite from the conductor posts, and the wiring pattern has no surface coating; (2) a flexible wiring board having on at least one side thereof the pads for connection to the conductor posts and including a wiring pattern with surface coating applied on the flexible portion but no surface coating applied on the multilayer portion, and (3) an adhesive layer having a flux function, wherein the conductor posts and pads are connected by a metal or an alloy, and the wiring patterns are electrically connected.